

AP9435GJ-VB Datasheet

P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$V_{DS}(V)$ $R_{DS(on)}(\Omega)$		Q _g (Typ.)			
- 30	0.056at V _{GS} = - 10 V	- 20	19 nC			
- 30	0.072 at V _{GS} = - 4.5 V	- 15	19110			

FEATURES

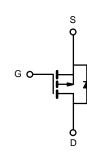
- Halogen-free
- Trench Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested



RoHS

APPLICATIONS

- Load Switch
- · Notebook Adaptor Switch



P-Channel MOSFET

TO-25	1	
G D	s	Drain Connected to Drain-Tab
Top Viev	N	

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V _{DS}	- 30	V			
Gate-Source Voltage	V_{GS}	± 20	v			
	T _C = 25 °C		- 20			
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	I _D	- 15			
Continuous Diain Curient (1) = 130°C)	T _A = 25 °C	'D	-7.9 ^{a, b}			
	T _A = 70 °C]	- 5.6 ^{a, b}	A		
Pulsed Drain Current	I _{DM}	- 60	_ ^			
Continuous Source-Drain Diode Current	T _C = 25 °C	1.	- 20			
Continuous Source-Diam Diode Current	T _A = 25 °C	- I _S	- 7.9 ^{a, b}			
Avalanche Current	L = 0.1 mH	I _{AS}	- 20			
Single-Pulse Avalanche Energy		E _{AS}	20	mJ		
	T _C = 25 °C	P _D	20			
Maximum Power Dissipation	T _C = 70 °C		15	w		
Maximum Fower Dissipation	T _A = 25 °C	ט י	2.7 ^{a, b}	VV		
	T _A = 70 °C		1.7 ^{a, b}			
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	46	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	C/VV	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on T_C = 25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 250A		- 34		mV/	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		5.3		°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.4		- 2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			- 1 - 5	μA	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ - 10 V, V _{GS} = - 10 V	- 20			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 6 A V _{GS} = - 4.5 V, I _D = - 4 A		0.056 0.072		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 6 A		28		S	
Dynamic ^b	0.0	20 1 2				L	
Input Capacitance	C _{iss}			1150			
Output Capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		205		pF	
Reverse Transfer Capacitance	C _{rss}			140			
Total Gate Charge	Q_g	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -6 \text{ A}$		27	43	nC	
-				19	25		
Gate-Source Charge	Q_{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -6 \text{ A}$		6			
Gate-Drain Charge	Q_{gd}			12			
Gate Resistance	R_{g}	f = 1 MHz	0.5	2.2	4.4	Ω	
Turn-On Delay Time	t _{d(on)}			13	25	ns	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		12	24		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		40	70		
Fall Time	t _f			9	18		
Turn-On Delay Time	t _{d(on)}			48	80		
Rise Time	t _r	V_{DD} = - 15 V, R_L = 1.5 Ω		92	160		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -6$ A, $V_{GEN} = -4.5$ V, $R_g = 1$ Ω		34	60		
Fall Time	l Time t _f			19	35		
Drain-Source Body Diode Characteris	stics						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.1	Α	
Pulse Diode Forward Current	I _{SM}				- 60		
Body Diode Voltage	V_{SD}	$I_{S} = -3 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			27	45	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = -6 A, dl/dt = 100 A/μs, T _{.I} = 25 °C		16	27	nC	
Reverse Recovery Fall Time	t _a	i _F - · σ Λ, αι/αι = 100 Λ/μs, 1 _J = 25 C		12		ns	
Reverse Recovery Rise Time	t _b			15			

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

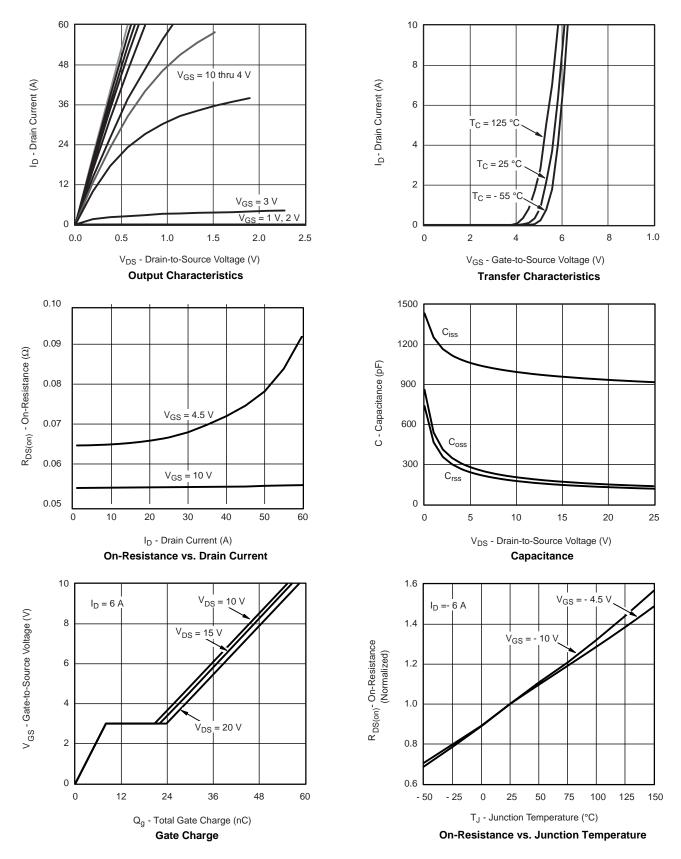
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a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

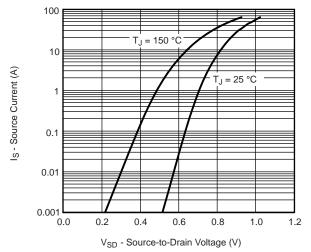


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

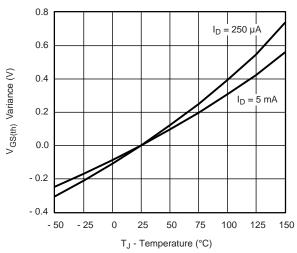




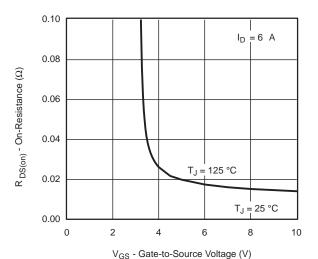
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



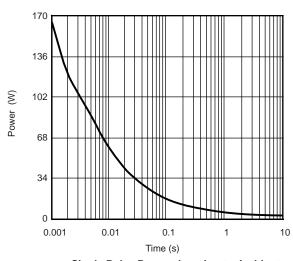
Source-Drain Diode Forward Voltage



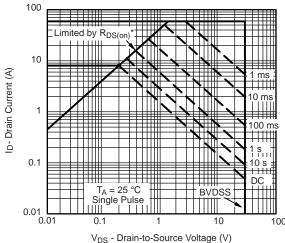
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

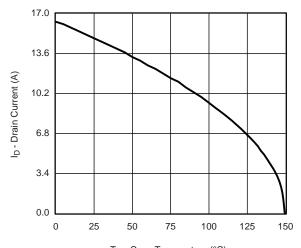


* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

Safe Operating Area

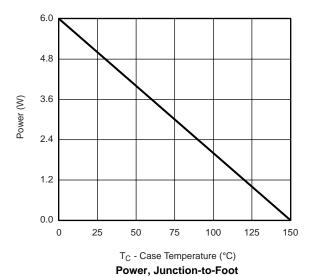


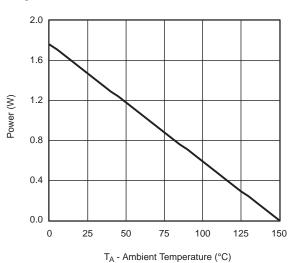
MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



 $T_{\mbox{\scriptsize C}}$ - Case Temperature (°C)

Current Derating*





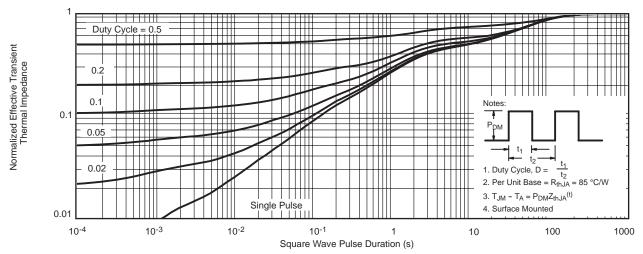
Power Derating, Junction-to-Ambient

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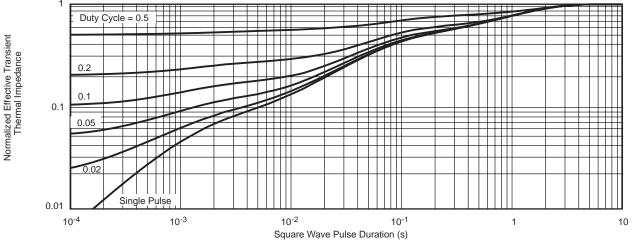
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



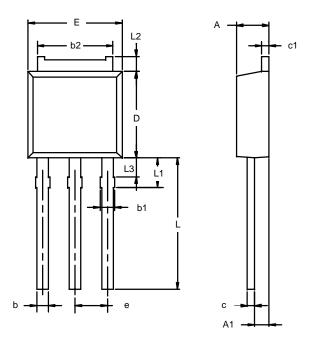
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



TO-251AA



Note: Dimension L3 is for reference only.

	MILLIM	IETERS	INCHES		
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A 1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28	BSC	0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	

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